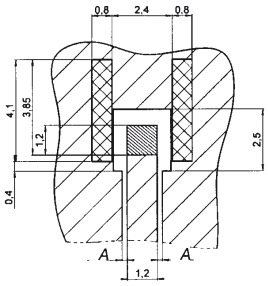
UMP

ASSEMBLY INSTRUCTIONS

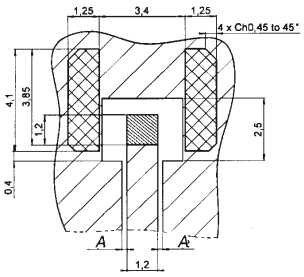
M02

RECEPTACLE SOLDERING PATTERNS FOR COPLANAR LINE



H2 Type Receptacle

PART NUMBER
R107 003 010



H3 Type Receptacle

PART NUMBER
R107 303 040

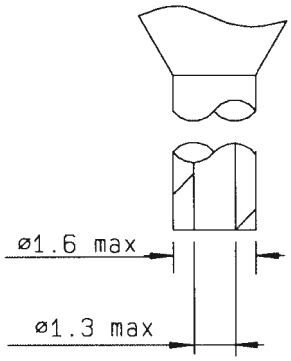
PCB THICKNESS (MM)	COPLANAR LIGNE A (MM)
0.8	0.183
1.0	0.190
1.2	0.195
1.6	0.20

Gold over Nickel prefered for solder paste
Gold can be replaced by tin lead (see test report SC2000.02.6587)

Gold over Nickel contact area free of any surface contaminant

Ground + varnish

SMT NOZZLE



Automated pick and place machines use standard tooling to peel the antistatic film off. Sometimes the "A" dimension of this tool is shorter than the overall "B" width between the two legs of the receptacle. There is therefore a risk for the two legs being deformed while they pass through the tool during the suction operation. The user must then widen the "A" dimension of the peeling tool.

